ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAK® SO-8 SOLDER PROCESS					
STRESS	**SAMPLE SIZE**	**DEVICE HR./CYC**	**CONDITION**	**TOTAL FAILS**	**FAIL PERCENTAGE**
BOND INT	400	200 000	200 °C + N2	0	0
HAST	2956	295 600	130 °C, 85 % RH	0	0
Pressure Pot	3332	319 872	121°, 15 PSIG	0	0
Solder DUNK	1217	3651	260 °C, 10 s	0	0
Solderability	165	1320	883 M2003	0	0
Temp. Cycle	5500	2 625 300	-55 °C to 150 °C	0	0

For technical questions, contact: pmostechsupport@vishay.com
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